IN THE CLAIMS

1. (Cancelled)

2. (Previously presented) A socket, comprising:

a socket body arranged to load first and second memory modules in the same direction while the socket body remains detached from a circuit board;

a first conductor arranged to connect a contact on a first surface of the first memory module to a contact on a first surface of the second memory module; and

a second conductor arranged to connect a contact on a second surface of the first memory module to a contact on a second surface of the second memory module.

3. (Cancelled)

4. (Previously presented) A through socket adapted to load a plurality of memory modules, comprising:

a through socket body arranged to load a first memory module, a second memory module, and a third memory module, said first, second and third memory modules being loaded in a base socket mounted to a board;

a first conductor arranged to connect a contact on a first surface of the first memory module to a contact on a first surface of the second memory module;

a second conductor arranged to connect a contact on a second surface of the second memory module to a contact on the first surface of the third memory module; and

a third conductor arranged to connect a contact on a second surface of the first memory module to a contact on a second surface of the third memory module;

wherein the through socket is structured to load said memory modules either above or to the side of said base socket mounted on said board.

5-25. (Cancelled)

26. (Previously presented) A memory module socket, comprising:

a socket body arranged to load first and second memory modules in the same direction while said socket body remains detached from a circuit board;

a first conductor arranged to connect a plurality of adjacent contacts on a first surface of the first memory module to a plurality of adjacent contacts on a first surface of the second memory module; and

a second conductor arranged to connect a plurality of adjacent contacts on a second surface of the first memory module to a plurality of adjacent contacts on a second surface of the second memory module.

27. (Previously presented) The socket of claim 26, wherein the socket body is arranged to load the first and second memory modules in opposite directions.

28. (Cancelled)

29. (Previously presented) The socket of claim 26 wherein the socket body is arranged to load a second memory module in the same direction.

30-31. (Cancelled)

32. (Withdrawn) A multi-socket memory system, comprising:

a base socket arranged to load a first memory module having first and second surfaces, said base socket including:

(i) a first conductor arranged to connect a plurality of adjacent contacts on the first surface of the first memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of the first memory module;

a through socket arranged to load said first memory module and a second memory module having first and second surfaces, said through socket including:

(i) a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of the first memory module to a plurality of adjacent contacts on the first surface of the second memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of the first memory module to a plurality of adjacent contacts on the second surface of the second memory module; and

a turn-around socket arranged to load a second memory module and including a conductor arranged to connect to a plurality of adjacent contacts on the first surface of the

second memory module and a plurality of adjacent contacts on the second surface of the second memory module.

33. (Withdrawn) The multi-socket system of claim 32 wherein:

the base socket is attached to a board and structured to load a first memory module orthogonal to said board; and

the through socket is arranged to load said first memory module and a second memory module in a loading plane substantially orthogonal to said board.

34. (Withdrawn) The multi-socket system of claim 32 wherein:

the base socket is attached to a board and structured to load a first memory module substantially parallel to said board; and

the through socket is arranged to load said first memory module and a second memory module in a loading plane substantially parallel to said board.

35. (Withdrawn) The multi-socket system of claim 32 wherein:

the base socket is attached to a board and structured to load a first memory module substantially parallel to said board; and

the through socket is arranged to load said first memory module and a second memory module in a substantially stacked arrangement.

36. (Withdrawn) A multi-socket memory system structured to load N memory modules, comprising:

a base socket arranged to load a first memory module having first and second surfaces, said base socket including:

(i) a first conductor arranged to connect a plurality of adjacent contacts on the first surface of the first memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of the first memory module;

a plurality of through sockets, each through socket arranged to load at least two joined memory modules each having first and second surfaces, each of said plurality of through sockets including:

(i) a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of the at least first joined memory module to a plurality of adjacent contacts on the first surface of the at least second joined memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of the at least first joined memory module to a plurality of adjacent contacts on the second surface of the at least second joined memory module; and

a turn-around socket arranged to load Nth memory module and including a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of Nth memory module and to a plurality of adjacent contacts on the second surface of Nth memory module.

37. (Withdrawn) The multi-socket system of claim 36 wherein:

the base socket is attached to a board and structured to load a first memory module orthogonal to said board; and

the plurality of through sockets is arranged to load first joined memory module and second joined memory module in a loading plane substantially orthogonal to said board.

38. (Withdrawn) The multi-socket system of claim 36 wherein:

the base socket is attached to a board and structured to load first memory module substantially parallel to said board; and

at least one of said plurality of through sockets is arranged to load first joined memory module and second joined memory module in a loading plane substantially parallel to said board.

39. (Withdrawn) The multi-socket system of claim 36 wherein:

the base socket is attached to a board and structured to load a first memory module substantially parallel to said board; and

at least one of said plurality of through sockets is arranged to load first joined memory module and joined second memory module in a substantially stacked arrangement.

40. (Withdrawn) A multi-socket memory system, comprising:

base socket arranged to load a first memory module having first and second surfaces, said base socket including:

(i) a first conductor arranged to connect a plurality of adjacent contacts on the first surface of the first memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of the first memory module;

first through socket arranged to load first and second memory modules each having first and second surfaces, said first through socket including:

(i) a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of first memory module to a plurality of adjacent contacts on the first surface of second memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of first memory module to a plurality of adjacent contacts on the second surface of second memory module;

second through socket arranged to load at second, third and fourth memory modules each having first and second surfaces, said second through socket including:

(i) a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of second memory module to a plurality of adjacent contacts on the first surface of third memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the second surface of second memory module to a plurality of adjacent contacts on the first surface of fourth third memory module, and

(iii) a third conductor arranged to connect to a plurality of adjacent contacts on the second surface of third memory module to a plurality of adjacent contacts on the second surface of fourth memory module; and

turn-around socket arranged to load third and fourth memory modules and including:

(i) a first conductor arranged to connect to a plurality of adjacent contacts on the first surface of third memory module to a plurality of adjacent contacts on the second surface of third memory module, and

(ii) a second conductor arranged to connect a plurality of adjacent contacts on the first surface of fourth memory module to a plurality of adjacent contacts on the second surface of fourth memory module.

41. (Withdrawn) The multi-socket system of claim 40 wherein:

the base socket is attached to a board and structured to load first memory module substantially parallel to said board; and

first and second through sockets are arranged to load second, third and fourth memory modules in a substantially stacked arrangement.